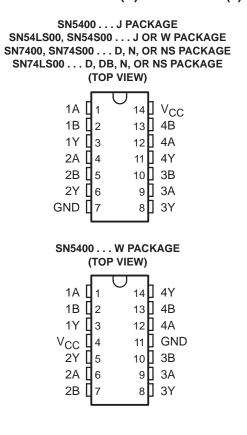
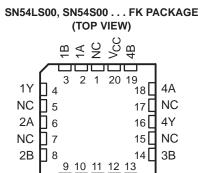
SN5400, SN54LS00, SN54S00 SN7400, SN74LS00, SN74S00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES SDLS025B - DECEMBER 1983 - REVISED OCTOBER 2003

Package Options Include Plastic Small-Outline (D, NS, PS), Shrink Small-Outline (DB), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) DIPs



Also Available as Dual 2-Input **Positive-NAND Gate in Small-Outline (PS)** Package

SN74LS00, SI	N74S00 . (TOP VII		S PACKAGE
1A [1	8	V _{CC}
1B [2	7	2B
1Y [3	6	2A
GND [4	5	2Y



ЯС

ЗA

З

GND 것 NC - No internal connection

description/ordering information

These devices contain four independent 2-input NAND gates. The devices perform the Boolean function $Y = \overline{A \bullet B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SDLS025B - DECEMBER 1983 - REVISED OCTOBER 2003

description/ordering information (continued)

т _А	PACK	(AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
			SN7400N	SN7400N
	PDIP – N	Tube	SN74LS00N	SN74LS00N
			SN74S00N	SN74S00N
		Tube	SN7400D	7400
		Tape and reel	SN7400DR	7400
		Tube	SN74LS00D	1.000
	SOIC – D	Tape and reel	SN74LS00DR	LS00
0°C to 70°C		Tube	SN74S00D	000
		Tape and reel	SN74S00DR	S00
			SN7400NSR	SN7400
	SOP – NS	Tape and reel	SN74LS00NSR	74LS00
			SN74S00NSR	74S00
	000 00		SN74LS00PSR	LS00
	SOP – PS	Tape and reel	SN74S00PSR	S00
	SSOP – DB	Tape and reel	SN74LS00DBR	LS00
			SNJ5400J	SNJ5400J
	CDIP – J	Tube	SNJ54LS00J	SNJ54LS00J
			SNJ54S00J	SNJ54S00J
FF00 1- 40500			SNJ5400W	SNJ5400W
–55°C to 125°C	CFP – W	Tube	SNJ54LS00W	SNJ54LS00W
			SNJ54S00W	SNJ54S00W
	LCCC – FK	Tube	SNJ54LS00FK	SNJ54LS00FK
	LUCC - FK	Jube	SNJ54S00FK	SNJ54S00FK

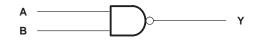
ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

	INPU	JTS	OUTPUT
ĺ	Α	В	Y
ĺ	Н	Н	L
	L	Х	Н
	Х	L	Н

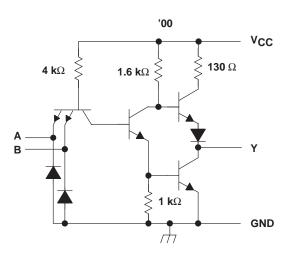
logic diagram, each gate (positive logic)

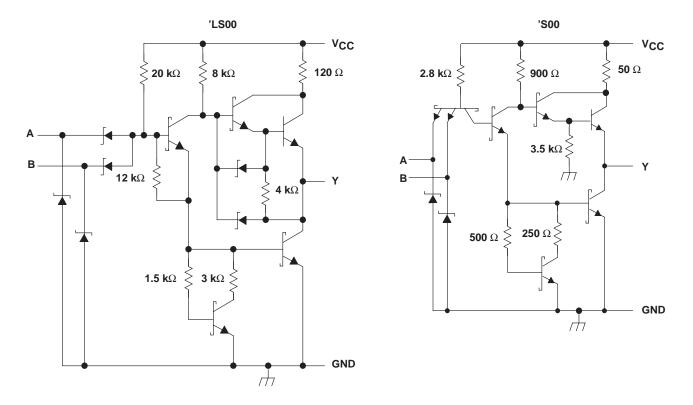




SN5400, SN54LS00, SN54S00 SN7400, SN74LS00, SN74S00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES SDLS025B - DECEMBER 1983 - REVISED OCTOBER 2003

schematic





Resistor values shown are nominal.



SDLS025B - DECEMBER 1983 - REVISED OCTOBER 2003

absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Input voltage: '00, 'S00		V
Package thermal impedance, θ_{JA} (see Note 2):	D package 86°C/ DB package 96°C/ N package 80°C/	W W
	NS package 76°C/ PS package 95°C/	W
Storage temperature range, T _{stg}	-65°C to 150°	°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Voltage values are with respect to network ground terminal.

2. The package termal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN5400			SN7400		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-0.4			-0.4	mA
IOL	Low-level output current			16			16	mA
Т _А	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN5400						
PARAMETER		TEST CONDITIO	NSŦ	MIN	TYP§	MAX	MIN	ΤΥΡ§	MAX	UNIT
VIK	$V_{CC} = MIN,$	I _I = -12 mA				-1.5			-1.5	V
VOH	$V_{CC} = MIN,$	V _{IL} = 0.8 V,	I _{OH} = -0.4 mA	2.4	3.4		2.4	3.4		V
VOL	$V_{CC} = MIN,$	V _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
lj	$V_{CC} = MAX,$	V _I = 5.5 V				1			1	mA
IIН	$V_{CC} = MAX,$	V _I = 2.4 V				40			40	μA
۱ _{IL}	$V_{CC} = MAX,$	$V_{I} = 0.4 V$				-1.6			-1.6	mA
IOS [¶]	$V_{CC} = MAX$			-20		-55	-18		-55	mA
ICCH	$V_{CC} = MAX,$	$V_{I} = 0 V$			4	8		4	8	mA
ICCL	$V_{CC} = MAX,$	V _I = 4.5 V			12	22		12	22	mA

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

§ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

¶ Not more than one output should be shorted at a time.



SDLS025B - DECEMBER 1983 - REVISED OCTOBER 2003

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see Figure 1)

PARAMETER	PARAMETER FROM TO (INPUT) (OUTPUT)		TEST CO		UNIT			
	(INFOT)	(001201)			MIN	TYP	MAX	
^t PLH	A or B	v	R _L = 400 Ω,	C _I = 15 pF		11	22	ns
^t PHL	A OID	I	11 = 400 22,	0L = 13 pi		7	15	115

recommended operating conditions (see Note 4)

		S	N54LS0	0	S	N74LS0	0	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-0.4			-0.4	mA
IOL	Low-level output current			4			8	mA
Т _А	Operating free-air temperature	-55		125	0		70	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN54LS00			S			
PARAMETER VIK VOH VOL II IIH IIL		TEST CONDITIO	NST	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = MIN,$	I _I = -18 mA				-1.5			-1.5	V
VOH	$V_{CC} = MIN,$	$V_{IL} = MAX,$	I _{OH} = -0.4 mA	2.5	3.4		2.7	3.4		V
			$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	
VOL	$V_{CC} = MIN,$	V _{IH} = 2 V	$I_{OL} = 8mA$					0.35	0.5	V
lj	V _{CC} = MAX,	$V_{I} = 7 V$				0.1			0.1	mA
ΙIH	$V_{CC} = MAX,$	$V_I = 2.7 V$				20			20	μA
١L	V _{CC} = MAX,	$V_I = 0.4 V$				-0.4			-0.4	mA
IOS§	$V_{CC} = MAX$			-20		-100	-20		-100	mA
ICCH	V _{CC} = MAX,	$V_{I} = 0 V$			0.8	1.6		0.8	1.6	mA
ICCL	V _{CC} = MAX,	V _I = 4.5 V			2.4	4.4		2.4	4.4	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

§ Not more than one output should be shorted at a time.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see Figure 1)

PARAMETER	RAMETER FROM TO TEST CONDITIONS		_	SN54LS00 SN74LS00				
	(INPUT)	(001201)		MIN	TYP	MAX		
^t PLH	A or B	v	RL = 2 kΩ, CL = 15 pF		9	15	ns	
^t PHL	AUD	I			10	15	115	



SDLS025B - DECEMBER 1983 - REVISED OCTOBER 2003

recommended operating conditions (see Note 5)

		S	SN54S00		S	N74S00		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-1			-1	mA
IOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				\$	SN54S00)	5			
PARAMETER		TEST CONDITIO	NST	MIN	түр‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = MIN,$	lj = -18 mA				-1.2			-1.2	V
VOH	$V_{CC} = MIN,$	$V_{IL} = 0.8 V,$	$I_{OH} = -1 \text{ mA}$	2.5	3.4		2.7	3.4		V
VOL	$V_{CC} = MIN,$	V _{IH} = 2 V,	I _{OL} = 20 mA			0.5			0.5	V
Ц	$V_{CC} = MAX,$	V _I = 5.5 V				1			1	mA
IIН	$V_{CC} = MAX,$	V _I = 2.7 V				50			50	μA
۱L	V _{CC} = MAX,	$V_{I} = 0.5V$				-2			-2	mA
IOS§	$V_{CC} = MAX$			-40		-100	-40		-100	mA
ICCH	V _{CC} = MAX,	$V_{I} = 0 V$			10	16		10	16	mA
ICCL	V _{CC} = MAX,	V _I = 4.5 V			20	36		20	36	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

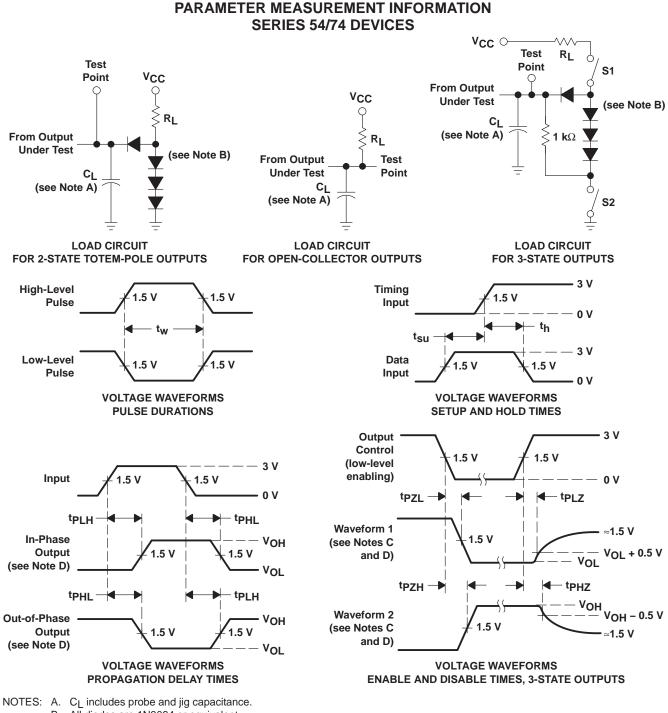
§ Not more than one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

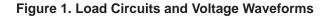
PARAMETER	FROM	TO	TEST CC	S S	UNIT			
	(INPUT)	(OUTPUT)			MIN	TYP	MAX	
^t PLH	A or B	v	R _L = 280 Ω,	C ₁ = 15 pF		3	4.5	ns
^t PHL	AUB	l l		0L = 10 pi		3	5	115
^t PLH	A or B	Y	R ₁ = 280 Ω,	$C_{1} = 50 pF$		4.5		ns
^t PHL	A OF D		NL = 200 32,	0L = 30 bi		5		113



SDLS025B - DECEMBER 1983 - REVISED OCTOBER 2003



- B. All diodes are 1N3064 or equivalent.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. S1 and S2 are closed for tPLH, tPHZ, and tPLZ; S1 is open and S2 is closed for tPZH; S1 is closed and S2 is open for tPZL. E. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O \approx 50 Ω ; t_r and t_f \leq 7 ns for Series
- 54/74 devices and t_r and $t_f \le 2.5$ ns for Series 54S/74S devices.
- F. The outputs are measured one at a time with one input transition per measurement.







28-Aug-2010

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
JM38510/00104BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
JM38510/00104BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
JM38510/07001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
JM38510/07001BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
JM38510/30001B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
JM38510/30001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
JM38510/30001BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
JM38510/30001SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
JM38510/30001SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SN5400J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SN54LS00J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SN54S00J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SN7400D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN7400DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN7400DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN7400N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributo or Sales Office
SN7400N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	Samples Not Availabl
SN7400NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributo or Sales Office
SN74LS00D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
SN74LS00DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI	Samples Not Availabl
SN74LS00DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LS00DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LS00DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples



28-Aug-2010

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LS00DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
SN74LS00DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
SN74LS00DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LS00DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LS00DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LS00J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	Samples Not Availabl
SN74LS00N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributo or Sales Office
SN74LS00NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributo or Sales Office
SN74LS00NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LS00NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LS00PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LS00PSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LS00PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74S00D	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Samples Not Availabl
SN74S00DE4	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Samples Not Availabl
SN74S00DG4	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Samples Not Availab
SN74S00N	NRND	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Samples Not Availabl
SN74S00N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	Samples Not Availabl
SN74S00NE4	NRND	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Samples Not Availab



Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74S00NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74S00NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74S00NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SNJ5400J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ5400W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ5400WA	OBSOLETE	CFP	WA	14		TBD	A42	N / A for Pkg Type	Samples Not Available
SNJ54LS00FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
SNJ54LS00J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ54LS00W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ54S00FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
SNJ54S00J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ54S00W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and package die adhesive used between the die and package die adhesive used between the die adhesive used betwee

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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28-Aug-2010

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN5400, SN54LS00, SN54LS00-SP, SN54S00, SN7400, SN74LS00, SN74S00 :

• Catalog: SN7400, SN74LS00, SN54LS00, SN74S00

• Military: SN5400, SN54LS00, SN54S00

• Space: SN54LS00-SP

NOTE: Qualified Version Definitions:

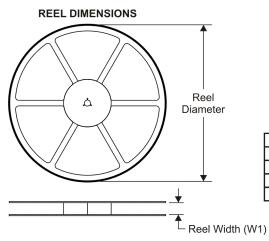
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

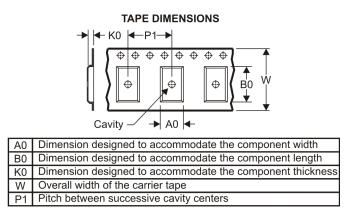
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS00DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS00DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS00NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS00PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74S00NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

23-Jul-2010



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS00DBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LS00DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS00NSR	SO	NS	14	2000	346.0	346.0	33.0
SN74LS00PSR	SO	PS	8	2000	346.0	346.0	33.0
SN74S00NSR	SO	NS	14	2000	346.0	346.0	33.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



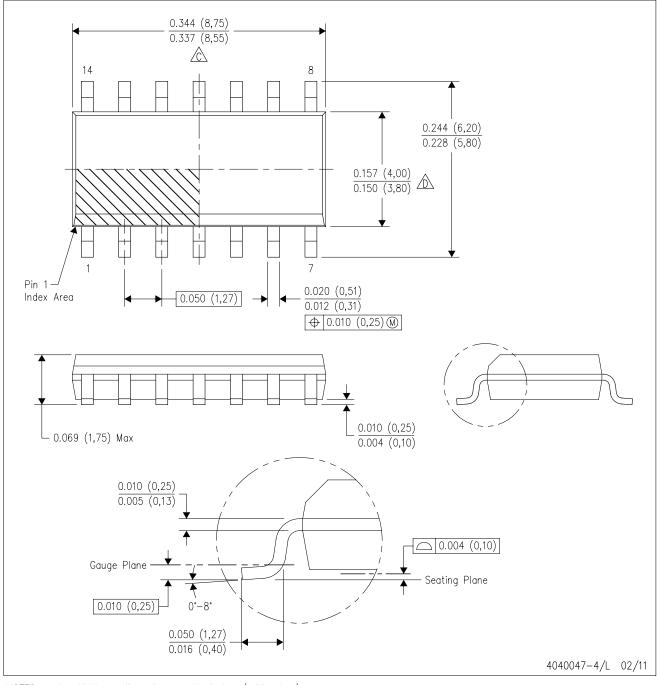
NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

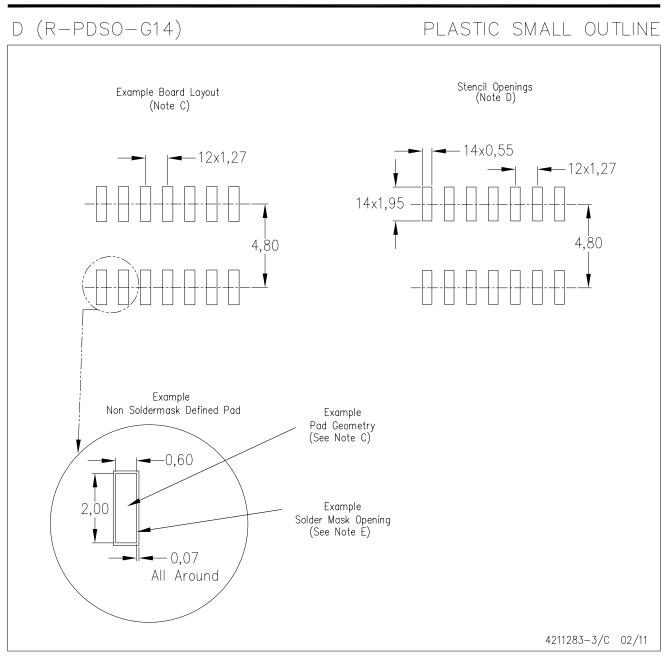
PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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